

**METHOD AND APPARATUS FOR REDUCING SUBSTRATE EDGE
EFFECTS IN ELECTRON LENSES**

Abstract of the Disclosure

One embodiment disclosed pertains to a method for inspecting a substrate. The method includes inserting the substrate into a holding place of a substrate holder, moving the substrate holder under an electron beam, and applying a voltage to a conductive element of the substrate holder. The voltage applied to the conductive element reduces a substrate edge effect. Another embodiment disclosed relates to an apparatus for holding a substrate that reduces a substrate edge effect. The apparatus includes a holding place for insertion of the substrate and a conductive element. The conductive element is positioned so as to be located within a gap between an edge of the holding place and an edge of the substrate.